

## P-Channel Enhancement Mode MOSFET

### 1. Product Information

#### Features

- Advanced trench technology
- Excellent  $R_{DS(ON)}$
- Low gate charge

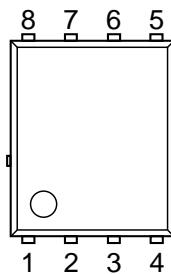
#### Pin Description

Pin	Description
1,2,3	Source(S)
4	Gate(G)
5,6,7,8	Drain(D)

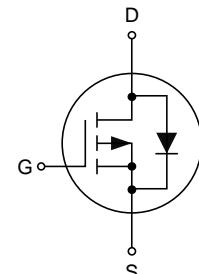
#### Applications

- Brushless motor
- Load switch
- Uninterruptible power supply

#### Simplified Outline



#### Symbol



Top View  
PDFN5x6-8L

#### Quick reference

$V_{DS} = -100$  V

$I_D = -80$  A

$R_{DS(ON)} \leq 25$  mΩ@ $V_{GS}=10$  V (Type: 20 mΩ)

### 2. Package Marking and Ordering Information

Product name	Package	Marking	Reel size	Tape width	Quantity(pcs)
KJ80P10G	PDFN5x6-8L	80P10 YWWXXX	13"	12 mm	5000

### 3. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Values	Unit
$V_{DS}$	Drain-Source Voltage	-100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current @ $T_c=25^\circ\text{C}$ <sup>1</sup>	-80	A
	Continuous Drain Current @ $T_c=100^\circ\text{C}$	-56	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-300	A
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	174	mJ
$I_{AS}$	Avalanche Current	-50	A
$P_D$	Total Power Dissipation @ $T_c=25^\circ\text{C}$ <sup>4</sup>	280	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient <sup>1</sup>	62	°C/W
$R_{\theta JC}$	Thermal Resistance from Junction to Case <sup>1</sup>	0.65	°C/W

#### 4. Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

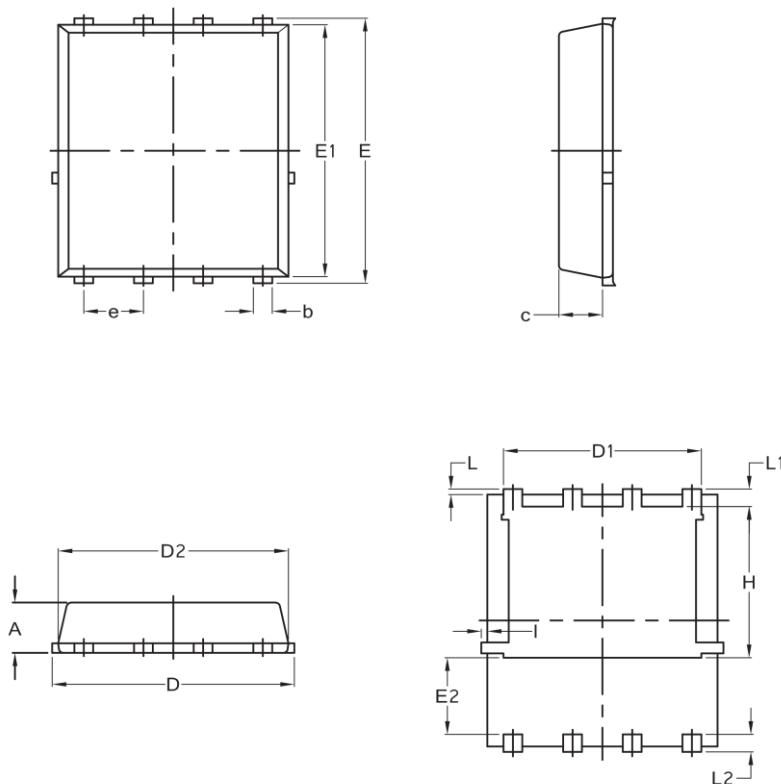
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0 \text{ V}, I_{\text{D}}=-250 \mu\text{A}$	-100	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-100 \text{ V}, V_{\text{GS}}=0 \text{ V}$	-	-	-1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0 \text{ V}, V_{\text{GS}}=\pm 20 \text{ V}$	-	-	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250 \mu\text{A}$	-1.0	-1.6	-2.5	V
$R_{\text{DS}(\text{on})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=-10 \text{ V}, I_{\text{D}}=-20 \text{ A}$	-	20	25	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5 \text{ V}, I_{\text{D}}=-10 \text{ A}$	-	25	30	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0 \text{ V}, V_{\text{DS}}=-50 \text{ V}, f=1.0 \text{ MHz}$	-	4230	-	pF
$C_{\text{oss}}$	Output Capacitance		-	388	-	
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	26	-	
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-50 \text{ V}, I_{\text{D}}=-5 \text{ A}, R_{\text{G}}=6 \Omega, V_{\text{GS}}=-10 \text{ V}$	-	26	-	ns
$t_{\text{r}}$	Turn-on Rise Time		-	78	-	
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	200	-	
$t_{\text{f}}$	Turn-off Fall Time		-	210	-	
<b>Gate Charge Characteristics</b>						
$Q_{\text{g}}$	Total Gate Charge	$V_{\text{DD}}=-50 \text{ V}, I_{\text{D}}=-5 \text{ A}, V_{\text{GS}}=-10 \text{ V}$	-	80	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	15.6	-	
$Q_{\text{gd}}$	Gate-Drain Charge		-	17.2	-	
<b>Diode Characteristics</b>						
$I_{\text{s}}$	Continuous Body Diode Current		-	-	-80	A
$I_{\text{SM}}$	Pulse Diode Forward Current		-	-	-280	A
$V_{\text{SD}}$	Body Diode Voltage	$I_{\text{SD}}=-30 \text{ A}, V_{\text{GS}}=0 \text{ V}$	-	-	-1.2	V
$T_{\text{rr}}$	Reverse Recovery Time	$I_{\text{F}}=-5 \text{ A}, dI/dt=100 \text{ A}/\mu\text{s}$	-	208	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		-	560	-	nC

Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2 OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. The  $E_{\text{AS}}$  data shows Max. rating. The test condition is  $V_{\text{DD}} = -72 \text{ V}, V_{\text{GS}} = -10 \text{ V}, L = 0.1 \text{ mH}, I_{\text{AS}} = -50 \text{ A}$ .
4. The power dissipation is limited by  $150^\circ\text{C}$  junction temperature.
5. The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$ , in real applications, should be limited by total power dissipation.

## 5. Package Mechanical Data

### PDFN5x6-8L Package



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.0382
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	-	0.0630	-
e	1.270 BSC		0.050 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	-	0.18	-	0.0070